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(54) SUPERCONDUCTING DEVICE, METHOD OF MANUFACTURING SUPERCONDUCTING DEVICE, AND LAMINATED BODY

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(57)ABSTRACT

A superconducting device includes: a substrate; a through hole provided in the substrate; a through electrode provided in the through hole, the through hole including a first portion and a second portion provided between the first portion and an inner wall surface of the through hole, in which the second portion is formed of a material including a first metal exhibiting superconductivity at a temperature lower than a criteria; a junction electrode electrically coupled to the through electrode, the junction electrode having at least a part provided outside the through hole and being formed of a material including a second metal exhibiting superconductivity at a temperature lower than a criteria; and a partition wall provided between the through electrode and the junction electrode and being formed of a material including the first metal, wherein a melting point of the first metal is higher than that of the second metal.

